

IN THE U.S. PATENT OFFICE AND TRADEMARK OFFICE

In re Application of

J. Heyen

Confirmation No. 4998

Serial No. 10/567,337

Examiner: Patton

Filed: 9/11/06

Art Unit: 2822

For: Multichip Circuit Module and Method for the Production Thereof

Request to Correct USPTO Records Concerning the Spelling of Applicant's Name and
Request the Issuance of a Supplemental Notice of Allowance

Box: Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached is a copy of the Notice of Allowance mailed November 29, 2007 in which applicant's name is "misspelled". The correct spelling is:

Johann HEYEN

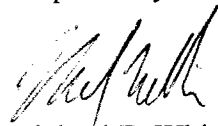
not Heyan as it appears on the Notice of Allowance; the correction is shown on the attached Notice of Allowance.

Also attached is the first page of WO 2005/015632 (attachment A) a copy of the executed Declaration/Power of Attorney (attachment B), both showing the correct spelling as HEYEN.

It is therefore requested that a Supplemental Notice of Allowance be forwarded to the undersigned with the correct spelling of HEYEN

If any fees are due with the filing of this request, please charge Deposit Account 50-2041.

Respectfully submitted,



Michael E. Whitham
Reg. No. 32,635

Date: Dec. 13, 2007

Whitham Curtis Christofferson
& Cook, PC
11491 Sunset Hills Road - #340
Reston, VA 20190
703/787-9400
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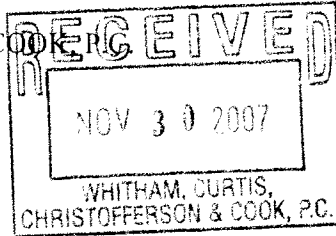


UNITED STATES PATENT AND TRADEMARK OFFICE

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NOTICE OF ALLOWANCE AND FEE(S) DUE

30743 7590 11/29/2007
WHITHAM, CURTIS & CHRISTOFFERSON & COOK, P.C.
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SUITE 340
RESTON, VA 20190



EXAMINER	
PATTON, PAUL E	
ART UNIT	PAPER NUMBER

2822
DATE MAILED: 11/29/2007

APPLICATION NO	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/567,337	09/11/2006	Johann Heyen <i>Heyen</i>	031C0278AA	4998

TITLE OF INVENTION: MULTICHIP CIRCUIT MODULE AND METHOD FOR THE PRODUCTION THEREOF

APPLN. TYPE	SMALL ENTITY	ISSUE FEE DUE	PUBLICATION FEE DUE	PREV. PAID ISSUE FEE	TOTAL FEE(S) DUE	DATE DUE
nonprovisional	NO	\$1440	\$300	\$0	\$1740	02/29/2008

THE APPLICATION IDENTIFIED ABOVE HAS BEEN EXAMINED AND IS ALLOWED FOR ISSUANCE AS A PATENT. PROSECUTION ON THE MERITS IS CLOSED. THIS NOTICE OF ALLOWANCE IS NOT A GRANT OF PATENT RIGHTS. THIS APPLICATION IS SUBJECT TO WITHDRAWAL FROM ISSUE AT THE INITIATIVE OF THE OFFICE OR UPON PETITION BY THE APPLICANT. SEE 37 CFR 1.313 AND MPEP 1308.

THE ISSUE FEE AND PUBLICATION FEE (IF REQUIRED) MUST BE PAID WITHIN THREE MONTHS FROM THE MAILING DATE OF THIS NOTICE OR THIS APPLICATION SHALL BE REGARDED AS ABANDONED. THIS STATUTORY PERIOD CANNOT BE EXTENDED. SEE 35 U.S.C. 151. THE ISSUE FEE DUE INDICATED ABOVE DOES NOT REFLECT A CREDIT FOR ANY PREVIOUSLY PAID ISSUE FEE IN THIS APPLICATION. IF AN ISSUE FEE HAS PREVIOUSLY BEEN PAID IN THIS APPLICATION (AS SHOWN ABOVE), THE RETURN OF PART B OF THIS FORM WILL BE CONSIDERED A REQUEST TO REAPPLY THE PREVIOUSLY PAID ISSUE FEE TOWARD THE ISSUE FEE NOW DUE.

HOW TO REPLY TO THIS NOTICE:

I. Review the SMALL ENTITY status shown above.

If the SMALL ENTITY is shown as YES, verify your current SMALL ENTITY status:

A. If the status is the same, pay the TOTAL FEE(S) DUE shown above.

B. If the status above is to be removed, check box 5b on Part B - Fee(s) Transmittal and pay the PUBLICATION FEE (if required) and twice the amount of the ISSUE FEE shown above, or

If the SMALL ENTITY is shown as NO:

A. Pay TOTAL FEE(S) DUE shown above, or

B. If applicant claimed SMALL ENTITY status before, or is now claiming SMALL ENTITY status, check box 5a on Part B - Fee(s) Transmittal and pay the PUBLICATION FEE (if required) and 1/2 the ISSUE FEE shown above.

II. PART B - FEE(S) TRANSMITTAL, or its equivalent, must be completed and returned to the United States Patent and Trademark Office (USPTO) with your ISSUE FEE and PUBLICATION FEE (if required). If you are charging the fee(s) to your deposit account, section "4b" of Part B - Fee(s) Transmittal should be completed and an extra copy of the form should be submitted. If an equivalent of Part B is filed, a request to reapply a previously paid issue fee must be clearly made, and delays in processing may occur due to the difficulty in recognizing the paper as an equivalent of Part B.

III. All communications regarding this application must give the application number. Please direct all communications prior to issuance to Mail Stop ISSUE FEE unless advised to the contrary.

IMPORTANT REMINDER: Utility patents issuing on applications filed on or after Dec. 12, 1980 may require payment of maintenance fees. It is patentee's responsibility to ensure timely payment of maintenance fees when due.



A

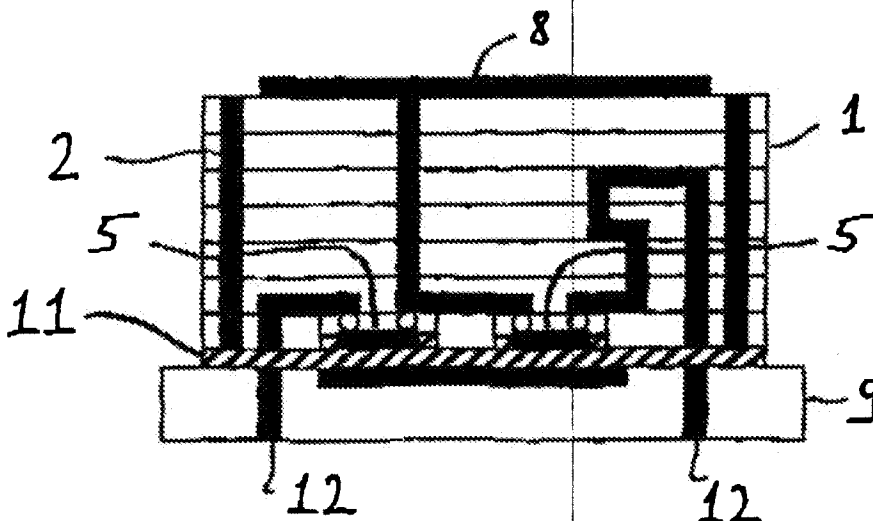
- (51) International patent classification⁷: H01L 23/373 (71) Applicant (for all designated States except US): TECHNISCHE UNIVERSITÄT BRAUNSCHWEIG CAROLO-WILHELMINA [DE/DE]; Pockelsstrasse 14, 38106 Braunschweig (DE).
- (21) International application number: PCT/DE2004/001576
- (22) International filing date: 20 July 2004 (20.07.2004)
- (25) Language of filing: German (72) Inventors; and (75) Inventors/Applicants (US only): HEYEN, Johann [DE/DE]; Ottobrunnerstrasse 22, 81737 Munich (DE).
- (26) Language of publication: German (74) Attorney: GERSTEIN, Hans, Joachim; Gramm, Lins & Partner GbR, Theodor-Heuss-Strasse 1, 38122 Braunschweig (DE).
- (30) Data relating to the priority: 103 36 171.5 7 August 2003 (07.08.2003)

[continued on next page]

As printed

(54) Title: MULTICHIP CIRCUIT MODULE AND METHOD FOR THE PRODUCTION THEREOF

(54) Bezeichnung: MULTICHIP-SCHALTUNGSMODUL UND VERFAHREN ZUR HERSTELLUNG DIERZU



(57) Abstract: The invention relates to a multichip circuit module comprising a main board (9), at least one carrier substrate (1) mounted on said main board (9) and electrically contacting said main board and at least one semiconductor chip (5) arranged on the carrier substrate (1) that is electrically contacted with the carrier substrate (1). The carrier substrate (1) has at least one cavity (4) on an assembly surface (3) for receiving at least one semiconductor chip (5), wherein the cavity (4) has connecting contacts (6) for associated bumps (7) of the semiconductor chip (5), the at least one semiconductor chip (5) is mounted with the bumps (7) in the connecting contacts (6) using

the flip-chip-technique, the assembly surface (3) of the carrier substrate (1) is placed on a contact surface (10) of the main board (9) and a filling material (11) is provided between the contact surface (10) of the main board (9) and the assembly surface (3) of the carrier substrate (1).

(57) Zusammenfassung: Bei einem Multichip-Schaltungsmodul mit einer Hauptplatine (9) mindestens einem auf der Hauptplatine (9) montierten und mit der Hauptplatine (9) elektrisch kontaktierten Trägersubstrat (1) und mindestens einem Halbleiterchip (5) auf dem Trägersubstrat (1), der mit dem Trägersubstrat (1) elektrisch kontaktiert ist, hat das Trägersubstrat (1) mindestens eine Kavität (4) an einer Montageoberfläche (3) zur Aufnahme mindestens eines Halbleiterchips (5), wobei in der Kavität (4) Anschlusskontakte (6) für zugeordnete Bumps (7) des Halbleiterchips (5) vorgesehen sind, der mindestens eine Halbleiterchip (5) in Flip-Chip-Technik mit den Bumps (7) an den Anschlusskontakten (6) montiert ist, und die Montageoberfläche (3) des Trägersubstrates (1) auf eine Kontaktoberfläche (10) der Hauptplatine (9) aufgebracht ist, und ein Füllmaterial (11) zwischen der Kontaktoberfläche (10) der Hauptplatine (9) und der Montageoberfläche (3) des Trägersubstrates (1) vorgesehen ist.

Docket No.
03100278AA

Declaration and Power of Attorney For Patent Application

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

MULTICHIP CIRCUIT MODULE AND METHOD FOR THE PRODUCTION THEREOF

the specification of which

(check one)

☐ is attached hereto.

☒ was filed on July 20 2004 as United States Application No. or PCT International Application Number PCT/DE2004/001576 and was amended on February 6, 2006 (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or (f), or 365(b) of any foreign application(s) for patent, or plant breeder's rights certificate(s), or 365(a) of any PCT International application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent, inventor's or plant breeder's rights certificate(s), or any PCT international application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

(Number)	(Country)	(Day/Month/Year Filed)	Priority Claimed
103 36 171.5	Germany	07 August 2003	<input checked="" type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	<input checked="" type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	<input checked="" type="checkbox"/>

I hereby claim the benefit under 35 U.S.C. Section 119(e) of any United States provisional application(s) listed below:

(Application Serial No.)

(Filing Date)

(Application Serial No.)

(Filing Date)

(Application Serial No.)

(Filing Date)

I hereby claim the benefit under 35 U. S. C. Section 120 of any United States application(s), or Section 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. Section 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, C. F. R., Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

PCT/DE2004/001576

29 JULY 2004

pending

(Application Serial No.)

(Filing Date)

(Status)

(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)

(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)

(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)

(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)

(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)

(patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. *(list name and registration number)*

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Marshall M. Curtis, Reg. No. 33,138

Clyde R Christofferson, Reg. No. 34,138

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Direct Telephone Calls to: *(name and telephone number)*
Michael E. Whitham 703-787-9400

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Date	August 3rd, 2006

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